

PATENT ASSIGNMENT

Electronic Version v1.1

Stylesheet Version v1.1

| SUBMISSION TYPE: | NEW ASSIGNMENT | | | | | | | | | | |
|---|------------------------------|---------------|--------------------------|----------------------------|------------------------------|--------------|-----------------------|-----------------------|-------------------|---------------------|---------|
| NATURE OF CONVEYANCE: | ASSIGNMENT | | | | | | | | | | |
| CONVEYING PARTY DATA | | | | | | | | | | | |
| <table border="1" style="width: 100%; border-collapse: collapse;"> <thead> <tr> <th style="width: 70%;">Name</th> <th style="width: 30%;">Execution Date</th> </tr> </thead> <tbody> <tr> <td>Tae Sik YUN</td> <td>11/11/2010</td> </tr> <tr> <td>Young Jun KU</td> <td>11/11/2010</td> </tr> </tbody> </table> | | Name | Execution Date | Tae Sik YUN | 11/11/2010 | Young Jun KU | 11/11/2010 | | | | |
| Name | Execution Date | | | | | | | | | | |
| Tae Sik YUN | 11/11/2010 | | | | | | | | | | |
| Young Jun KU | 11/11/2010 | | | | | | | | | | |
| RECEIVING PARTY DATA | | | | | | | | | | | |
| <table border="1" style="width: 100%; border-collapse: collapse;"> <tr> <td style="width: 20%;">Name:</td> <td>Hynix Semiconductor Inc.</td> </tr> <tr> <td>Street Address:</td> <td>San 136-1, Ami-ri, Bubal-eub</td> </tr> <tr> <td>City:</td> <td>Ichon-si, Gyeonggi-do</td> </tr> <tr> <td>State/Country:</td> <td>REPUBLIC OF KOREA</td> </tr> <tr> <td>Postal Code:</td> <td>467-860</td> </tr> </table> | | Name: | Hynix Semiconductor Inc. | Street Address: | San 136-1, Ami-ri, Bubal-eub | City: | Ichon-si, Gyeonggi-do | State/Country: | REPUBLIC OF KOREA | Postal Code: | 467-860 |
| Name: | Hynix Semiconductor Inc. | | | | | | | | | | |
| Street Address: | San 136-1, Ami-ri, Bubal-eub | | | | | | | | | | |
| City: | Ichon-si, Gyeonggi-do | | | | | | | | | | |
| State/Country: | REPUBLIC OF KOREA | | | | | | | | | | |
| Postal Code: | 467-860 | | | | | | | | | | |
| PROPERTY NUMBERS Total: 1 | | | | | | | | | | | |
| <table border="1" style="width: 100%; border-collapse: collapse;"> <thead> <tr> <th style="width: 30%;">Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>12970907</td> </tr> </tbody> </table> | | Property Type | Number | Application Number: | 12970907 | | | | | | |
| Property Type | Number | | | | | | | | | | |
| Application Number: | 12970907 | | | | | | | | | | |
| CORRESPONDENCE DATA | | | | | | | | | | | |
| <p>Fax Number: (703)579-0105</p> <p><i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i></p> <p>Phone: 703-496-5559</p> <p>Email: seungho.lee@echelaw.com</p> <p>Correspondent Name: Echelon Law Group, PC</p> <p>Address Line 1: 1919 Gallows Road., Suite 330</p> <p>Address Line 4: Vienna, VIRGINIA 22182</p> | | | | | | | | | | | |
| ATTORNEY DOCKET NUMBER: | SN101.HY125U | | | | | | | | | | |
| NAME OF SUBMITTER: | K. Kevin Mun | | | | | | | | | | |
| <p>Total Attachments: 2</p> <p>source=125-11-Assignment#page1.tif</p> <p>source=125-11-Assignment#page2.tif</p> | | | | | | | | | | | |

OP \$40.00 12970907

501382121

PATENT
REEL: 025515 FRAME: 0183

ASSIGNMENT

WHEREAS, We, the below named inventors (hereinafter referred to as "Assignors"), have made an invention entitled:

THREE-DIMENSIONAL STACKED SEMICONDUCTOR INTEGRATED CIRCUIT

for which we executed an application for United States Letters Patent

☐ concurrently herewith, or

☐ filed as Application No. _____ on _____, and

WHEREAS, Hynix Semiconductor Inc. (hereinafter referred to as "Assignee"), organized and operating under the laws of Republic of Korea, whose post office address is San 136-1, Ami-ri, Bubal-eub, Ichon-si, Gyeonggi-do 467-860, Republic of Korea, is desirous of securing the entire right, title, and interest in and to this invention in all countries throughout the world, and in and to the application for United States Letters Patent on this invention and the letters Patent to be issues upon this application;

NOW THEREFORE, be it known that, for good and valuable consideration the receipt of which from Assignee is hereby acknowledged, Assignors have sold, assigned, transferred, and set over, and do hereby sell, assign, transfer, and set over unto Assignee, its lawful successors and assigns, the entire right, title, and interest in and to this invention, this application, all divisions and continuations thereof, all Letters Patent of the United States which may be granted thereon, all reissues thereof, all rights to claim priority on the basis of this application, all applications for Letters Patent which may hereafter be filed for this invention in any foreign country, all Letters Patent which may be granted on this invention in any foreign country, and all extensions, renewals, and reissues thereof; and Assignors hereby authorize and request the Commissioner of Patents and Trademarks of the United States and any official of any foreign country whose duty it is to issue patents on applications as described above, to issue all Letters Patent for this invention to Assignee, its successors and assigns, in accordance with the terms of this Assignment;

AND, ASSIGNORS HEREBY covenant that Assignor has the full right to convey the interest assigned by this Assignment, and Assignors have not executed and will not execute any agreement in conflict with this Assignment;

AND, ASSIGNORS HEREBY further covenant and agree, without further consideration, that Assignors will communicate with Assignee, its successors and assigns, any facts known to Assignors respecting this invention and testify in any legal proceeding, sign all lawful papers when called upon to do so, execute and deliver any and all papers that may be necessary or desirable to perfect the title to this invention in said Assignee, its successors or assigns, execute all divisional, continuation, and reissue applications, make all rightful oaths and generally do everything possible to aid Assignee, its successors and assigns, to obtain and enforce proper patent protection for this invention in the United States and any foreign country, it being understood that any

expense incident to the execution of such papers shall be borne by the Assignee, its successors and assigns.

IN TESTIMONY WHEREOF, We have hereunto set our hands.

Signature of Inventor: Yun Tae Sik
Inventor(s) Name: YUN, Tae Sik
Residence: San 136-1, Ami-ri, Bubal-eub, Ichon-si,
Gyeonggi-do 467-860, Republic of Korea
Citizenship: Korean
Date: 2010. 11. 11

Signature of Inventor: Ku Young Jun
Inventor(s) Name: KU, Young Jun
Residence: San 136-1, Ami-ri, Bubal-eub, Ichon-si,
Gyeonggi-do 467-860, Republic of Korea
Citizenship: Korean
Date: 2010. 11. 11
